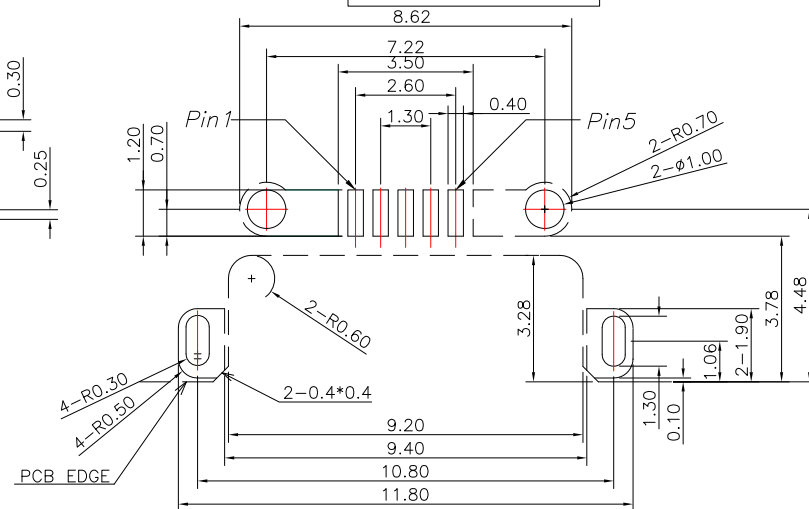
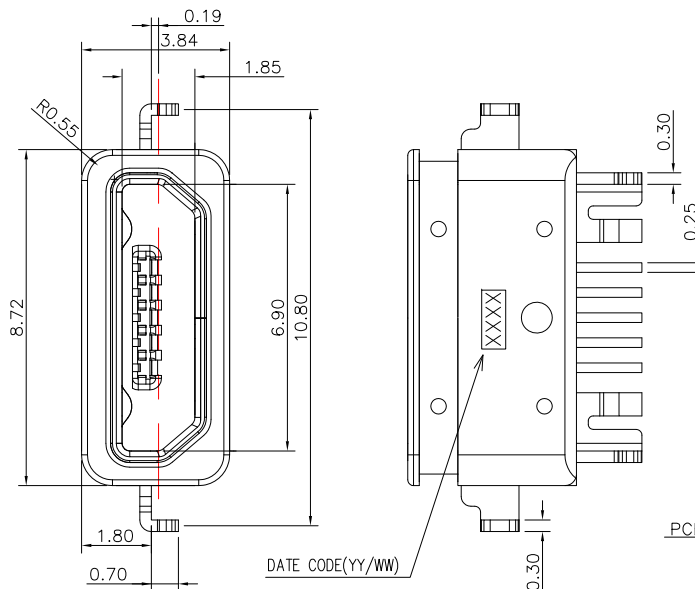
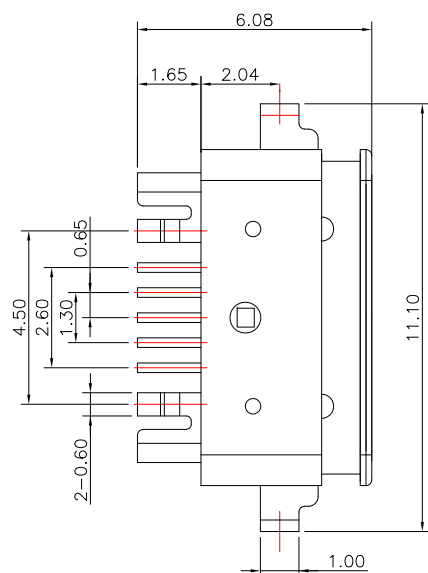
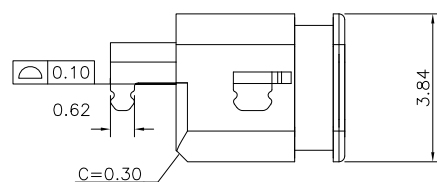


IP67



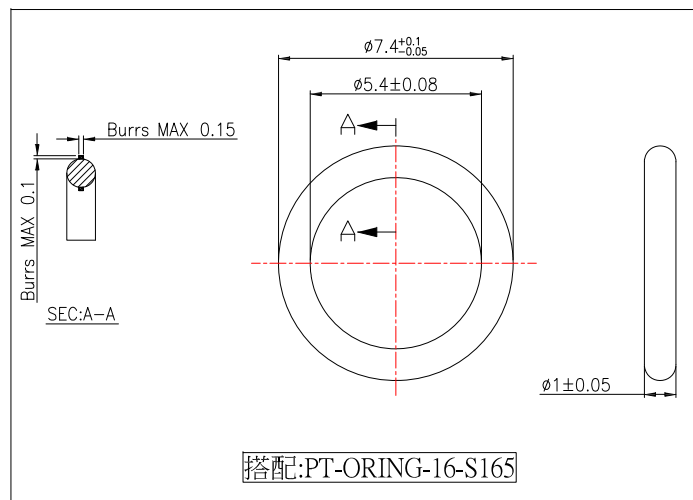
P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP13-x-S165

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



NOTES:

MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC
- 1.2 CONTACT: COPPER ALLOY
- 1.3 SHELL: SUS
- 1.4 O-RING: SILICON

FINISH:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.SPECIFICATION:
 - 3.1 RATING: 1.0A
 - 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 500 VAC
 - 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
 - 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

5	新增O-RING圖	Jack	102920	CONTACT建倚科技股份有限公司CONTACT TECHNOLOGY CORP. TOLERANCE UNLESS OTHERWISE STATED: Up to 5 ±0.2 Above 5 ~ 15 ±0.3 Above 15 ~ 30 ±0.4 Above 30 ~ 50 ±0.5 Angle ±0.3° 3RD. ANGEL'S  UNITS MM	DRAWN BY: DATE	MAT'L	TITLE	CONNECTOR		
5	刪除O-RING圖	Jack	040819		Jack Lu10/29/20					
4	更新樣式	Jack	032119		CHECKED BY: DATE	FINISH	MODLE	MICRO USB 5PF B TYPE 沉板 板上 H 1.8 IP67		
3	新增O-RING圖	Jack	112618		Jacky Chen10/29/20					
2	新增尺寸	Jack	073118		APPROVED BY: DATE	SCALE	1 : 1	DWG NO.	MRUSB-5B-WP13-x-S165	SIZE
1	更新為A0版	Jack	071718		Tony Kao10/29/20					
ITEM NO.	DESCRIPTION	DRAWN	DATE							
A	B	C	D	E	F	G	H	I	J	